

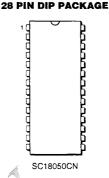
#### **FEATURES**

- ☐ AdLib Emulation
- ☐ Sound Blaster Emulation
- ☐ 4:1 ADPCM Compression and Decompression
- ☐ Record and Playback
- ☐ Single 5 Volt Power Supply☐ 28 pin Plastic Dip
- ☐ Low Power Dissipation
- ☐ Fully Static Operation

#### **GENERAL DESCRIPTION**

The SC18050 is a sound ROM that is used in conjunction with Sierra's SC18000 Audio System Controller, and the SC18025 Audio Processor to form the ST8000 chip set. When used in conjunction with the other chips the SC18050 enables AD Lib and Sound Blaster Emulation, 4:1 ADPCM compression and decompression, and record and playback.

The SC18050 is organized as 65,536 words by 8 bits. The device is fully TTL compatible on all inputs and outputs and uses a single 5 Volt power supply. The device is fully static, requiring no clock operation. When the chip is not enabled, the power supply current is reduced to a 150 uA maximum.



## **BLOCK DIAGRAM**

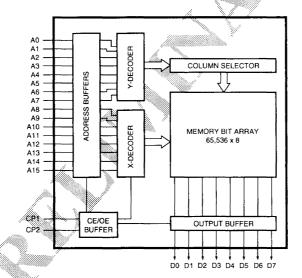


Figure 1. SC18050 (65,536 x 8) ROM

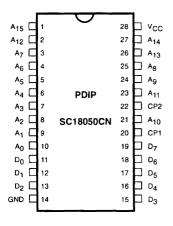
Sound Blaster is a registered trademark of Creative Labs Inc. AdLib is a registered trademark of AdLib Inc. ARIA is a trademark of Sierra Semiconductor.

Rev 0.91

## PIN DESCRIPTIONS

PIN NAME	PIN NUMBER	DESCRIPTION
A <sub>0</sub> -A <sub>15</sub>	10-3, 25-24, 21, 23, 2, 26-27, 1	Address inputs.
D <sub>0</sub> -D <sub>7</sub>	11-13, 15-19	Data outputs.
CP1, CP2	20, 22	Control pins.
V <sub>CC</sub>	28	+5V supply.
GND	14	Ground.

## **CONNECTION DIAGRAM**



# CAPACITANCE T<sub>A</sub> = 25°C, f = 1.0MHz

SYMBOL	PARAMETER	TEST CONDITIONS	TYP	мах	UNIT
C <sub>IN</sub>	Input capacitance	$V_{IN} = 0V$	5	5	pF
C <sub>OUT</sub>	Output capacitance	V <sub>IN</sub> = 0V	7	8	pF

#### **TRUTH TABLE**

(For simplicity, all control functions in the truth table are defined as active high.)

CP1 = CE/OE	CP2 = CE/OE	OUTPUTS	POWER
CE/OE active	CE/OE active	Data out	$I_{CC}$
CE inactive	X	High Z	$I_{SB}$
OE inactive	CE active	High Z	I <sub>CC</sub>
X	CE inactive	High Z	$I_{SB}$
CE active	OE inactive	High Z	I <sub>CC</sub>

#### **ABSOLUTE MAXIMUM RATINGS**

Ambient Temperature Under Bias – T <sub>A</sub>	-55°C to +125°C
Storage Temperature	-65°C to +150°C
Operating Temperature	+125°C
Input or Output Voltages	-0.3 to V <sub>CC</sub> +0.3V
Maximum V <sub>DD</sub>	-0.3V to 7V
Maximum Power	500mW

NOTE:

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only, and functional operation of the device at these or any other conditions beyond those listed in the "Recommended Operating Conditions" section of this specification is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

SYMBOL	PARAMETER	CC = 5V ± 10%, T <sub>A</sub> = 0°C to 70°C  TEST CONDITIONS	MIN	MAX	UNIT
V <sub>OL</sub>	Output LOW voltage	3.2mA I <sub>OL</sub>		0.4	V
V <sub>OH</sub>	Output HIGH voltage	-1.0mA I <sub>OH</sub>	2.4		v
$V_{IL}$	Input LOW voltage		-0.3	0.8	V
V <sub>IH</sub>	Input HIGH voltage		2.2	V <sub>CC</sub> +0.3	V
I <sub>LI</sub>	Input leakage current	$V_{IN} = 0V V_{CC}$	-1.0	1.0	μА
I <sub>LO</sub>	Output leakage current	$V_0 = 0V$ to $V_{CC}$ , outputs deselected	-10	10	μА
I <sub>CC1</sub>	Power supply current – active	$I_0 = 0$ , TR = $t_{CYC}$ , duty = 100% V <sub>I</sub> = 0.8V or 2.2V		40	mA
I <sub>CC2</sub>	Power supply current - active	$I_0 = 0$ , TR = $t_{CYC}$ , duty = 100% $V_I = GND$ or $V_{CC}$		35	mA
I <sub>SB</sub>	Power supply current – standby	Chip in standby mode, $V_I = GND$ to $V_{CC}$		150	μA

NOTE: It is recommended that a high frequency bypass capacitor between the power supply pin and the ground pin be utilized.

## **AC TIMING DIAGRAMS**

SYMBOL	PARAMETER	MIN	MAX	UNIT
t <sub>AA</sub>	Address access time		200	ns
t <sub>OH</sub>	Output hold time	0		ns

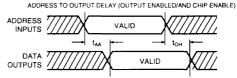


Figure 3.

SYMBOL	PARAMETER	MIN	MAX	UNIT
t <sub>OE</sub>	Output enable access		80	ns
t <sub>OEO</sub>	Disable time from Output Enable	0	70	ns

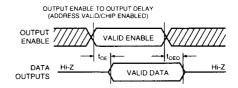


Figure 4.

SYMBOL	PARAMETER	MIN	MAX	UNIT
t <sub>CEO</sub>	Disable time fromChip Enable	0	70	ns
t <sub>ACE</sub>	Chip enable access time		200	ns

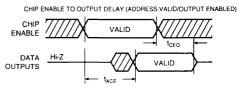


Figure 5.

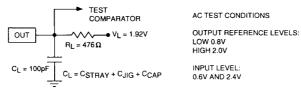


Figure 6. Test Load